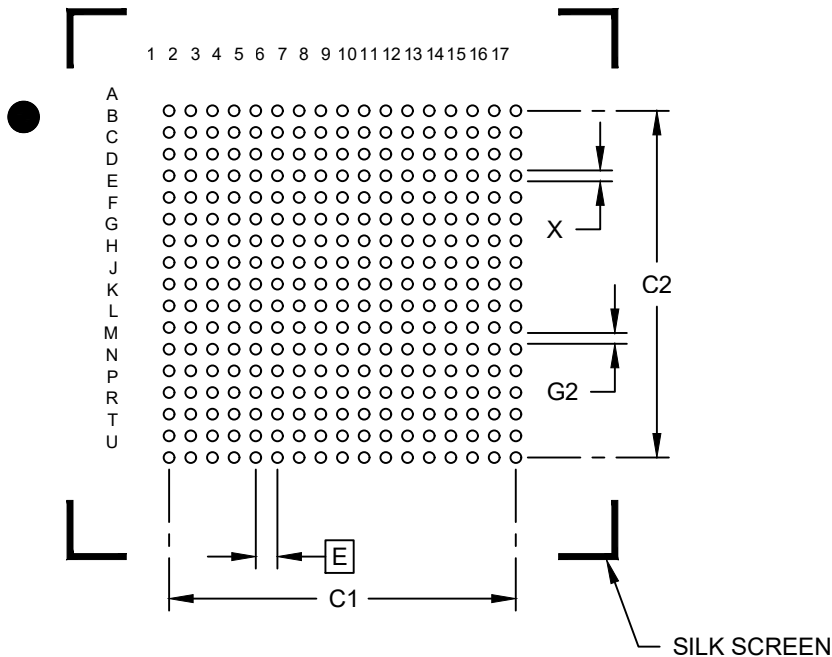


289-Ball Thin Fine-Pitch Ball Grid Array Package (8GW) - 9x9x1.2 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Diameter (X289)	X			0.25
Contact Pad to Contact Pad (X285)	G2	X.XX		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, please refer to current industry standard IPC-7093.